

Photosensors with front-end IC

S16429 series

Built-in gain-stabilized APD suitable for short pulse light detection

This device is for direct TOF (time-of-flight) distance measurement, integrating a Si APD and a transimpedance amplifier. A gain-stabilized APD (GS APD) is used, and there is little gain fluctuation relative to temperature fluctuation, so there is no need for a temperature sensor or microcontroller. It has an increased high-band cutoff frequency (S16429-01CT: 300 MHz) of the transimpedance amplifier compared to previous products, realizing high-speed response.

- Features

- Applications

- Stable gain against temperature fluctuations
- No gain adjustment according to individual differences required
- Built-in high-speed transimpedance amplifier S16429-01CT: 300 MHz S16429-02CT: 280 MHz
- Low noise
- No ringing

Structure

Parameter	Symbol	S16429-01CT	S16429-02CT	Unit
Detector	-	Si APD S15415-02	Si APD S15415-05	-
Photosensitive area*1	Α	ф0.2	φ0.5	mm
Package	-	Glass epoxy		
Sealing material	-	Silicone resin		

*1: Area in which a typical gain can be obtained

- Absolute maximum ratings

Parameter	Symbol	Condition	Value	Unit
Supply voltage (for transimpedance amplifier)	Vcc max		4.0	V
Reverse voltage (for APD)	V_APD		0 to VBR	V
Photocurrent (DC)	IL max		0.2	mA
Incident pulse light level*2	Ppulse		5	W
Operating temperature	Topr	No dew condensation*3	-40 to +105	°C
Storage temperature	Tstg	No dew condensation*3	-40 to +125	°C
Transimpedance amplifier chip temperature	Tj		150	°C
Soldering temperature* ⁴	Tsol		260 (twice)	°C

*2: FWHM=1 ns (repetition frequency: 1 kHz)

*3: When there is a temperature difference between a product and the surrounding area in high humidity environments, dew condensation may occur on the product surface. Dew condensation on the product may cause deterioration in characteristics and reliability.

*4: Reflow soldering, JEDEC J-STD-020 MSL 4, see P.7

Note: Exceeding the absolute maximum ratings even momentarily may cause a drop in product quality. Always be sure to use the product within the absolute maximum ratings.

→ Distance measurement
 → Presence or absence of objects

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Electrical and optical characteristics [Ta=25 °C, Vcc=3.3 V, AC coupling + 50 Ω load, dark state]

Deveneeter	Cumbal Condition	Condition	S16429-01CT		S16429-02CT			11-24	
Parameter Symbol		Condition	Min.	Тур.	Max.	Min.	Тур.	Max.	Unit
Spectral response range	λ		400 to 1100		400 to 1100		nm		
Peak sensitivity wavelength	λр		-	840	-	-	840	-	nm
Photosensitivity	S	λ=905 nm, M=1	-	0.5	-	-	0.5	-	A/W
Breakdown voltage*5	Vbr	Vcc=0 V, ID=10 µA Gain_APD terminal: open ^{*6} *8	180	200	220	180	200	220	V
Operating reverse voltage	Vop	Gain-stabilized mode operation*7 *8	185 + 1.1 × (Ta opr - 25)*9	-	-	185 + 1.1 × (Ta opr - 25)* ⁹	-	-	V
Temperature coefficient of operating reverse voltage	ΔTVop	*8	0.95	1.1	1.25	0.95	1.1	1.25	V/°C
Dark current*5	Id	Gain-stabilized mode operation*7	-	20	200	-	40	400	pА
APD gain*5	М	Gain-stabilized mode operation ^{*7} λ =905 nm	40	50	60	40	50	60	-
Transimpedance amplifier gain	G	Differential	-	30	-	-	30	-	kV/A
Current consumption	Icc		-	45	65	-	45	65	mA
High-band cutoff frequency	fch		200	300	-	180	280	-	MHz
Equivalent input current noise*5	en	f=100 MHz	-	6	9	-	6	9	pA/Hz ^{1/2}
Output impedance*5	Zo	f=100 MHz	-	50	80	-	50	80	Ω
Maximum output voltage amplitude	Vp-p max	Differential	0.4	0.7	-	0.4	0.7	-	V
Supply voltage	Vcc		3.135	3.3	3.465	3.135	3.3	3.465	V
DC current rejection*5	Idc		1	-	-	1	-	-	mA

*4: APD gain is stabilized by connecting a constant current source to the anode (see P.5 "Temperature characteristics of output waveform").

*5: Reference values defined by simulation or characteristic evaluation

*6: Opening the Gain_APD terminal enables operation as a typical APD instead of a GS-APD

*7: Apply bias voltage to anode. IR anode limit=10 μA

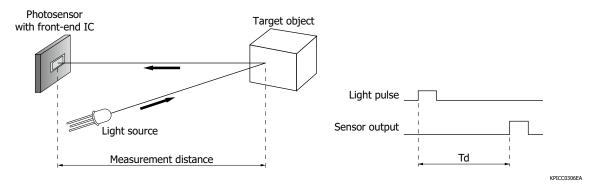
*8: Ta opr=assumed maximum operating temperature

*9: Characteristics for APD only

Distance measurement method

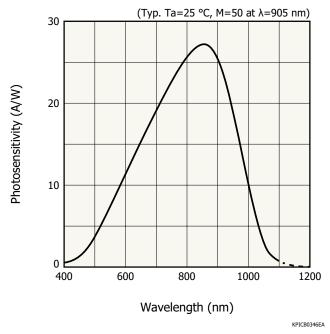
Distance L is calculated from the speed of light c and the time difference Td between the light source's light emission timing and sensor output.

 $L = (1/2) \times c \times Td$

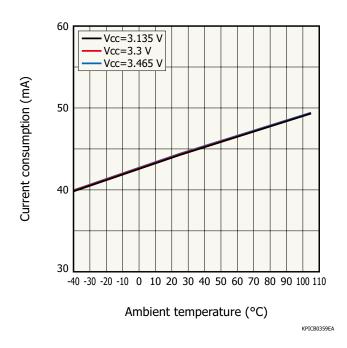


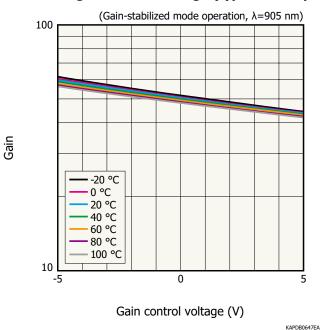


Spectral response

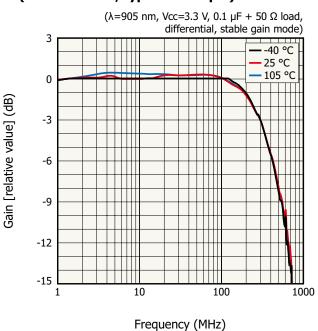


 Current consumption vs. ambient temperature (typical example)





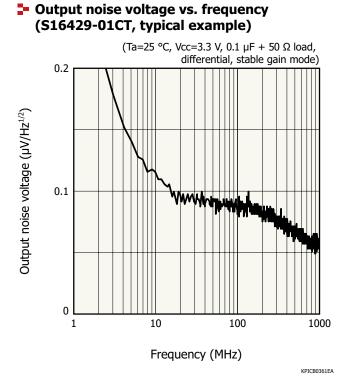
Frequency characteristics (S16429-01CT, typical example)



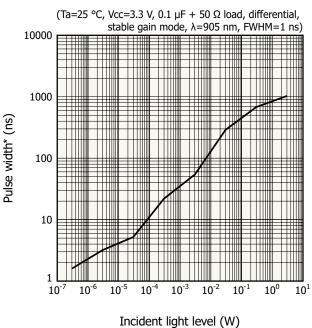
KPICB0360EA



Gain vs. gain control voltage (typical example)

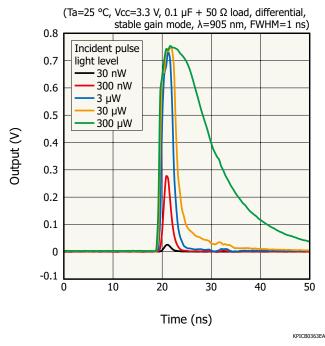


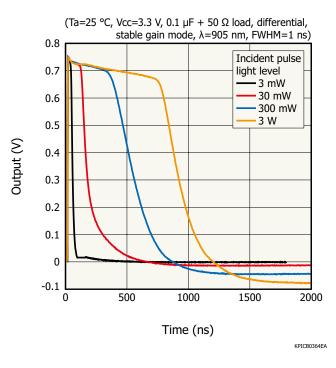
Output pulse width vs. incident light level (typical example)



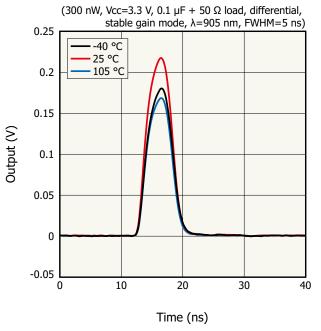
* Measured output voltage 200 mV as a threshold value KPICE0352EA

Output waveform (S16429-01CT, typical example)



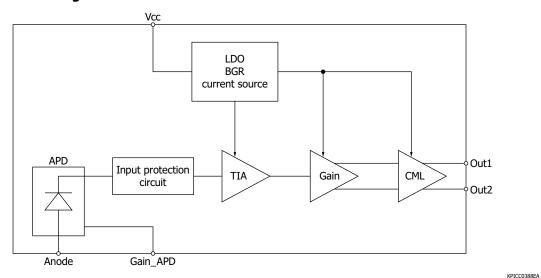






Temperature characteristics of output waveform (typical example)



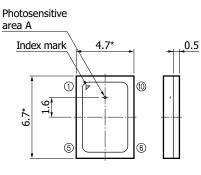


Block diagram

TIA (Transimpedance Amplifier) integrates DCFB (DC feedback) circuit. The DCFB circuit detects the DC component of photocurrent, and reduces the effects of background light through the differential processor.



Dimensional outline (unit: mm)



Photosensitive

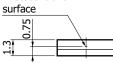
<u>(12 ×)</u> φ0.5

P1.0 × 3=3 4 Ó

0

Index mark

(3

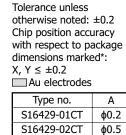


3.65

 \odot 6

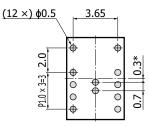
C n ®

0 10 0



KPICA0118EA

Recommended land pattern (unit: mm)



Tolerance unless otherwise noted: ±0.1 * Distance from package center to pad center KPICC0389EB

Precautions

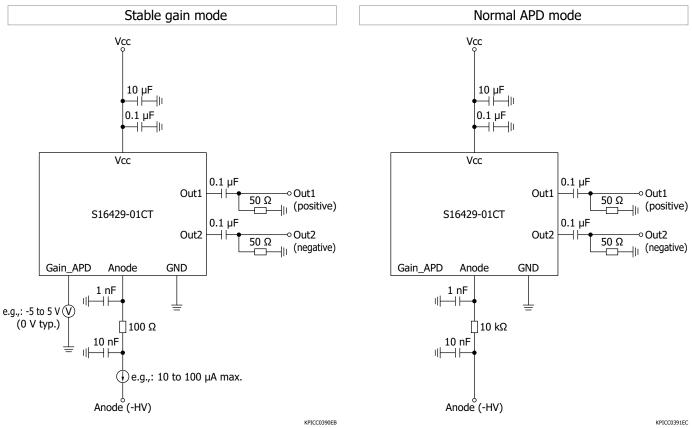
- · Apply high voltage to the anode terminal. Beware of electric shock.
- · Apply negative voltage with respect to GND (-165 V, etc.) to the anode terminal.
- The top of the package is silicone resin. Be careful not to pinch it too hard with metal tweezers, as this can cause cracks or flakes.



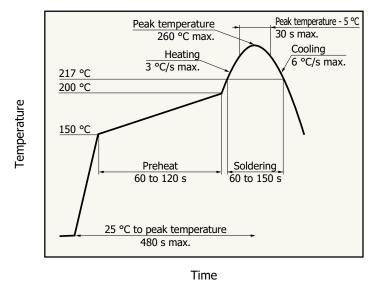
Pin connections

Din no	Function		
Pin no.	Function		
1	Gain_APD		
2	NC		
3	NC		
4	NC		
5	Out2 (negative)		
6	Out1 (positive)		
7	GND		
8	Vcc		
9	NC		
10	Anode		
11	GND		
12	GND		

Operating circuit example



Recommended reflow soldering conditions



KSPDB0419EA

- This product supports lead-free soldering. After unpacking, store it in an environment at a temperature of 30 °C or less and a humidity of 60% or less, and perform soldering within 72 hours.
- The effect that the product receives during reflow soldering varies depending on the circuit board and reflow oven that are used. When you set reflow soldering conditions, check that problems do not occur in the product by testing out the conditions in advance.

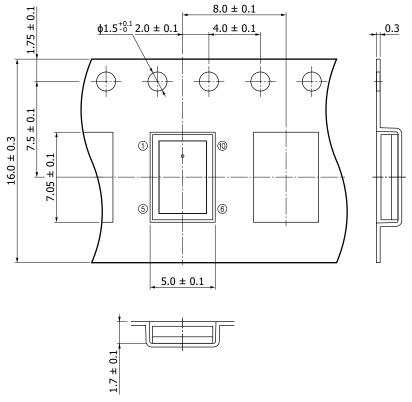


Reel packing specifications

Reel (conforms to JEITA ET-7200)

Outer diameter	Hub diameter	Tape width	Material	Electrostatic characteristics
φ254 mm	φ100 mm	16 mm	PS	Conductive

Embossed tape (unit: mm, material: PS, conductive)



KPICC0366EA

Packing quantity 1000 pcs/reel

Packing state

Reel and desiccant in moisture-proof packing (vacuum-sealed)



Related products

Si APD S15415 series

This is a surface mount type Si APD with the built-in photodetector chip of the S16429 series, mounted in a silicone COB package. This realizes constant gain without the need for temperature adjustment.

Features

- Built-in temperature compensation function
- Compact package: 2.0 × 1.8 × 0.85^t mm

High-speed response: cutoff frequency=500 MHz typ.

Type No.	Photosensitive area	Photosensor with front-end IC		
S15415-02	φ0.2 mm	S16429-01CT		
S15415-05		S16429-02CT		



Related information

www.hamamatsu.com/sp/ssd/doc_en.html

- Precautions
- Disclaimer
- · Precautions / Surface mount type products

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